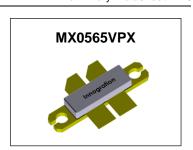
650W, 50V High Power RF LDMOS FETs

Description

The MX0565VPX is a 650-watt capable, high performance, unmatched LDMOS FET, designed for wide-band commercial and industrial applications with frequencies HF to 0.5 GHz. It can be used for both CW and pulse applications.

It is featured for high power and high ruggedness, suitable for Industrial, Scientific and Medical application, as well as FM radio, VHF TV and Aerospace applications.



Typical performance(on 325MHz test board with device soldered):

V_{DD} = 50 Volts, I_{DQ} = 200 mA, Pulsed CW.(100us,10%), Vgs=3.24V, Vds=50V,Idq=230mA

Freq (MHz)	P3dB (W)	Gain (dB)	Eff (%)
325	670	15.5	68

- Recommended driver: MR2002VP or MU1503V
- Application board for 2-30/27/40/225/325MHz upon request

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift

- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Suitable Applications

- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 160-230MHz (TV VHF III)
- 136-174MHz (Commercial ground communication)
- Laser Exciter
- Synchrotron
- MRI
- · Plasma generator
- · Weather Radar

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+135	Vdc
GateSource Voltage	V _{gs}	-10 to +10	Vdc
Operating Voltage	V _{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _c	+150	°C
Operating Junction Temperature	T _J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	Doug	0.00	0000
T _C = 85°C, T _J =200°C, DC test	RθJC	0.22	°C/W

Table 3. ESD Protection Characteristics

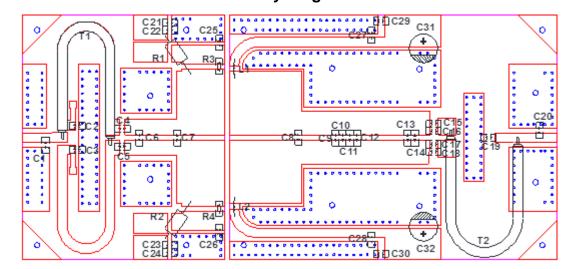
Test Methodology Class

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Human Body Model (per JESD22--A114) Class 2 Table 4. Electrical Characteristics (T_A = 25 °C unless otherwise noted) Characteristic Symbol Min Max Unit Typ DC Characteristics (per half section) Drain-Source Voltage 135 ٧ $V_{(BR)DSS}$ $V_{GS}=0$, $I_{DS}=1.0Ma$ Zero Gate Voltage Drain Leakage Current 1 IDSS μΑ $(V_{DS} = 75V, V_{GS} = 0 V)$ Zero Gate Voltage Drain Leakage Current I_{DSS} μΑ $(V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V})$ Gate--Source Leakage Current μΑ I_{GSS} $(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$ Gate Threshold Voltage 2.65 ٧ $V_{\text{GS}}(th)$ $(V_{DS} = 50V, I_D = 600 \mu A)$ Gate Quiescent Voltage ٧ 3.24 $V_{GS(Q)}$ $(V_{DD} = 50 \text{ V}, I_D = 230 \text{ mA}, \text{Measured in Functional Test})$ Drain source on state resistance Rds(on) 160 $\, m\Omega$ (Vds=0.1V, Vgs=10V) Common Source Input Capacitance CISS 295 рF $(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Common Source Output Capacitance 75 C_{oss} pF $(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Common Source Feedback Capacitance C_{RSS} 1.3 $(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$ Load Mismatch (In Innogration Test Fixture, 50 ohm system): V_{DD} = 50 Vdc, I_{DQ} = 230 mA, f = 350MHz, pulse width:100us, duty cycle:10%

Reference Circuit of Test Fixture Assembly Diagram

Load 10:1 All phase angles, at 650W Pulsed CW Output Power



No Device Degradation

Figure 1. Test Circuit Component Layout (325M)

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Table 1. Test Circuit Component Designations and Values (325MHz)

Component	Description	Suggested
		Manufacturer
C1,	20 pF	ATC800B
C2, C3, C4, C5, C15, C16, C17, C18,	470 pF	ATC800B
C22, C23, C27, C28		
C6, C11, C12, C13	10 pF	ATC800B
C7, C8, C9, C10, C14,	18 pF	ATC800B
C19, C20	4.7 pF	ATC800B
C21, C24, C25, C26, C29, C30	Ceramic multilayer capacitor, 10uF, 100V	
R1, R2	270 Ω, 1/4W	
R3, R4	13 Ω	1206
L1, L2	30nH Air core inductance	
C31, C32	Electrolytic Capacitor ,470uF,63V	
PCB	0.508mm [0.020"] thick, εr=3.48, Rogers RO43	50B, 1 oz. copper

TYPICAL CHARACTERISTICS

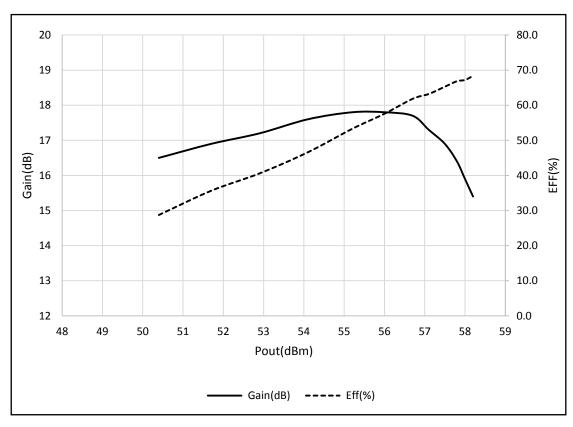
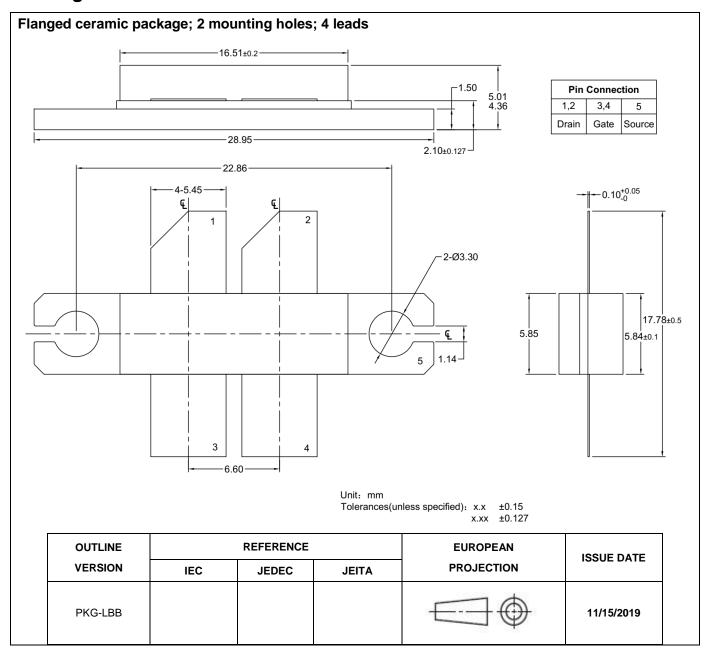


Figure 2: Power Gain and Drain Efficiency as Function of Pout (325MHz)

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Package Outline



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Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2019/12/17	Rev 1.0	Preliminary Datasheet Creation

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